Fufei An

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EDUCATION

University of Illinois at Urbana-Champaign (UIUC) Ph.D Candidate of Materials Sicence and Engineering Shanghai Jiao Tong University (SJTU)

Bachelor of Engineering in Materials Science and Engineering

WORKING EXPERIENCE

Analog Devices, Inc.

Senior Engineer, Product Engineering (Mfg.)

- Management of product sustaining activities which include driving product margin and performance improvement (yield, test time, quality, etc.) and cost reduction
- Lead cross functional collaborative efforts to optimize product positioning to meet business requirements

SKILLS

Fabrication Skills: Familiar with all the common fabrication processes for nanoelectronics, including (but not limited) Photolithography (Both traditional mask manual aligner and Heidelberg Maskless Aligner), Electron Beam Lithography (heavy user on both Raith system and Elionix system), Wet etching with HF/BOE/TMAH etc. and dry etching like Reactive Ion Etching (RIE) and Plasma enhanced ICP-RIE, Wet/Dry Oxidation, Metal depositions (E-beam evaporator, AJA sputtering system, thermal evaporator, etc.), Atomic Layer Deposition (ALD), Plasma-Enhanced Chemical Vapor Deposition (PECVD), etc.

Materials Characterizations and Measurements: Nanophoton Raman, Atomic Force Microscope (Cypher AFM), Scanning Electron Microscope (Hitachi SEM), Focused Ion Beam (Thermo Scios2 Dual-Beam SEM/FIB), Thermal Gravity Analysis (TGA), X-Ray Diffraction (XRD), X-ray photoelectron spectroscopy (XPS), Fourier Transform Infrared Spectroscopy (FTIR), Transmission Electron Microscope (TEM), Scanning transmission electron microscopy (STEM), Micromanipulator Probe Station (Keysight EasyExpert as the software), CRX-6.5K Probe Station, CHI650D (Electrochemical Workstation), Brunauer, Emmett and Teller (BET) Technique, Gas Chromatograph, etc.

Computer Competencies: Klarity ACE, Data Suite, Exensio, Avalon, OriginLab, Adobe Photoshop, Matlab, Python, LabVIEW, Blender, Klayout, DigitalMicrograph, Solidworks, Microsoft, etc.

SELECTED AWARDS

Editors' Choice 2024 from Communications Engineering	Jan.2025
Mavis Future Faculty Fellows by the Grainger College of Engineering (2023-2024)	Apr.2023
PPG-MRL Graduate Research Assistantship at the Materials Research Laboratory	Dec.2021
Undergraduate Overseas Research Scholarship	Oct.2017
Prominent Performance Award for Academic Conference of Chun-Tsung Program	Dec.2016
Arawana Scholarship, Awarded by Arawana Charity Foundation	Sep.2016
Second Prize, Contemporary Undergraduate Mathematical Contest in Modeling	Sep.2016
Elite (Liu Yongling) Scholarship, Awarded by Elite Industrial Holdings Ltd.	Sep.2015

Aug.2018-May.2024 Advisor: Qing Cao Sep.2014-Jun.2018 Advisor: Shenmin Zhu

May.2024-Present Global Operations & Technology

PUBLICATIONS

- Hsien-Nung Wang¹, Fufei An¹, Cindy Wong, Kaijun Yin, Jiangnan Liu, Yihan Wang, Jian-Min Zuo, Andre Schleife, and Qing Cao*. Solution-processable ordered defect compound semiconductors for high-performance electronics. *Science Advances 10, eadr8636 (2024)*, *Feature Article of Science Advances*.
- Fufei An, C.Wang, V.H.Pham, A.Borisevich, J.Qian, K.Yin, S.Pidaparthy, B.Robinson, A-S.Chou, J.Lee, J.Weidman, S.Natesakhawat, H.Wang, A.Schleife, J-M.Zuo, C.Matranga, and Q.Cao*. Ultrathin quasi-2D amorphous carbon dielectric prepared from solution precursor for nanoelectronics. *Communications Engineering 2, 93 (2023), Editors' Choice 2024.*
- Jinsong Cui, **Fufei An**, Jiangchao Qian, Yuxuan Wu, Luke L. Sloan, Saran Pidaparthy, Jian-Min Zuo, Qing Cao^{*}. CMOS-Compatible and Scalable Electrochemical Synaptic Transistor Arrays for Deep-Learning Accelerator. *Nature Electronics (2023): 1-9.*
- Yi Zhang, Jinsong Cui, Kuan-Yu Chen, Shanny H. Kuo, Jaishree Sharma, Rimsha Bhatta, Zheng Liu, Austin Ellis-Mohr, **Fufei An**, Jiahui Li, Qian Chen, Kari D. Foss, Hua Wang, Yumeng Li, Annette M. McCoy, Gee W. Lau, Qing Cao^{*}. A Smart Coating with Integrated Physical-Antimicrobial and Strain-Mapping Functionalities for Orthopaedic Implants. *Science Advances 9, eadg7397 (2023)*.
- Yadong Xu¹, Ganggang Zhao¹, Liang Zhu, Qihui Fei, Zhe Zhang, Zanyu Chen, **Fufei An**, Yangyang Chen, Yun Ling, Peijun Guo, Shinghua Ding, Guoliang Huang, Pai-Yen Chen, Qing Cao, Zheng Yan. Pencil-paper on-skin electronics. *Proceedings of the National Academy of Sciences* 117-31(2020):18292-18301.
- Fufei An¹, Li, Yao¹, Haoran Wu, Shenmin Zhu, Chenyangzi Lin, Mengdan Xia, Kun Xue, Di Zhang, and Keryn Lian. A NiCo₂S₄/hierarchical porous carbon for high performance asymmetrical supercapacitor. *Journal of Power Sources* 427(2019): 138-144.
- Li, Yao¹, Mengdan Xia¹, **Fufei An**, Nianfang Ma, Xueliang Jiang, Shenmin Zhu, Dawei Wang, and Jun Ma. Superior removal of Hg (II) ions from wastewater using hierarchically porous, functionalized carbon. *Journal of hazardous materials* 371(2019): 33-41.
- Sun, Du¹, Yunfei Wang¹, Kenneth JT Livi, Chuhong Wang, Ruichun Luo, Zhuoqun Zhang, Hamdan Alghamdi, Chenyang Li, **Fufei An**, Bernard Gaskey, Tim Mueller, and Anthony Shoji Hall^{*}. Ordered Intermetallic Pd₃Bi Prepared by an Electrochemically Induced Phase Transformation for Oxygen Reduction Electrocatalysis. *ACS nano 13, no.9(2019): 10818-10825.*

PATENT APPLICATIONs

• Qing Cao, **Fufei An**, Christopher Matranga, Congjun Wang, Viet Hung Pham. "2D amorphous carbon film assembled from graphene quantum dots" U.S. Patent Application No. 21-0366-US-PRO

CONFERENCE AND PRESENTATIONS

- Fufei An, Qing Cao. "Ultrathin Quasi-2D Amorphous Carbon Dielectric prepared from Solution Precursor for Nanoelectronics", 2024 MRS Spring Meeting.
- Congjun Wang, Viet Hung Pham, Fufei An, Christopher Matranga, Qing Cao. "Solution Processible Carbon Precursors for 2D Amorphous Carbon Dielectric", The Materials Science & Technology (MS&T) technical meeting and exhibition (2022).